





1|2 POWER SIGNAL POWER 5 P2 4 3 PΙ EΙ E PA PA Ε Ε Ε Ε Ε

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ITEM CONTACT QTY NO. TYPE Ε 24 SIGNAL PΑ POWER НΑ 2 HOLD - DOWN

3 |

## CONNECTOR NOTES:

ROWS

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PRODUCT No.

51659-001

NOTE:(2)

(I.) HOUSING MATERIAL: GLASS FILLED HIGH TEMP THERMOPLASTIC PER UL94 V-0.

SIGNAL CONTACT MATERIAL: COPPER ALLOY POWER CONTACT MATERIAL: COPPER ALLOY

(2) 51659-001;51659-001LF;51659-001GLF PLATING SPEC. SEE PRINT:10064183

3. MANUFACTURER NAME, P/N, AND LOT CODE TO APPEAR ON THIS SURFACE.

## PCB NOTES:

4. ALL DIMENSIONS ARE BASIC UNLESS OTHERWISE SPECIFIED

5. ALL THROUGH HOLES ARE LOCATED WITH A TRUE POSITION OF 0.004"

6. ALL DIAMETERS ARE FINISHED HOLE SIZES

7. Ø 0.0453/1.151 DRILLED HOLES, PLATED WITH 0.0003/0.007 MIN. SnPb OVER 0.001/1.03 TO 0.003/0.08 Cu PLATING TO ACHIEVE A  $\emptyset$  0.040 $\pm$ 0.003/1.02 $\pm$ 0.07 HOLE.

mat'l code						tolerances unless otherwise specified					CU	STOM	ER	FC),								
ltr	ecn	no.	dr	do	ite		.XX±.01/0.X±0.3			0.3	COPY			www.fciconnect.com								
E						linear	.XXX±.005/0.XX±0.13				projec	tion		title		ΙP	+ 2	4S +	I P			
							.XXXX±.002/.XXX±.05			+		VERTICAL SOLDER RECEPTACLE										
						angles	ngles 0°		±2°		$\Psi$		VENTTONE SOLDEN NECETTACLE									
						dr	С. В	AROT	06-0	1-99	INC	\H/I	NANA	produ	ot fami	ily	P	WRBL	ADE	code		
				en		engr	J. B	J. BROWN 06-01-99		INCH/MM		size dwg no						213				
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PDM: Rev:Ē

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Pro/E

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